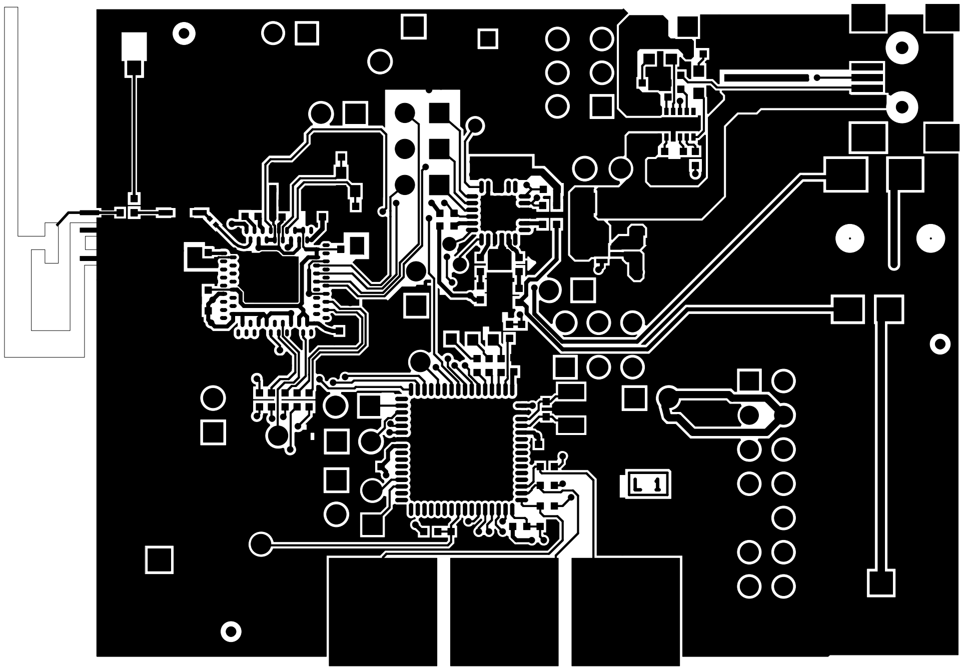


CUSTOMER NAME:
TEXAS INSTRUMENTS

BOARD NAME:
BT-MSP-AUDSOURCE

DESCRIPTION:
LAYER 1 - PRIMARY SIDE

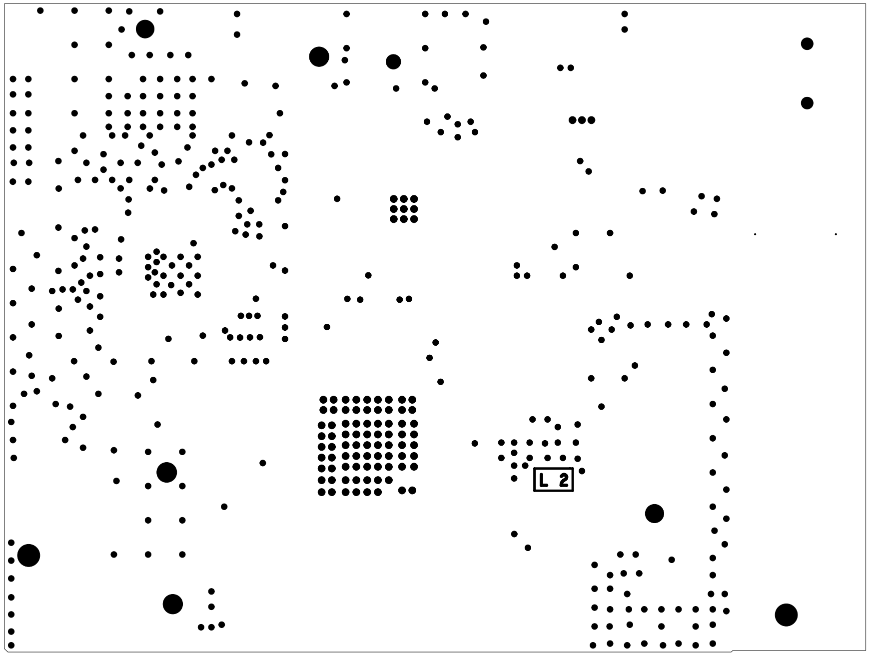
TI TICKET NO:
6576620

REV:
1.1

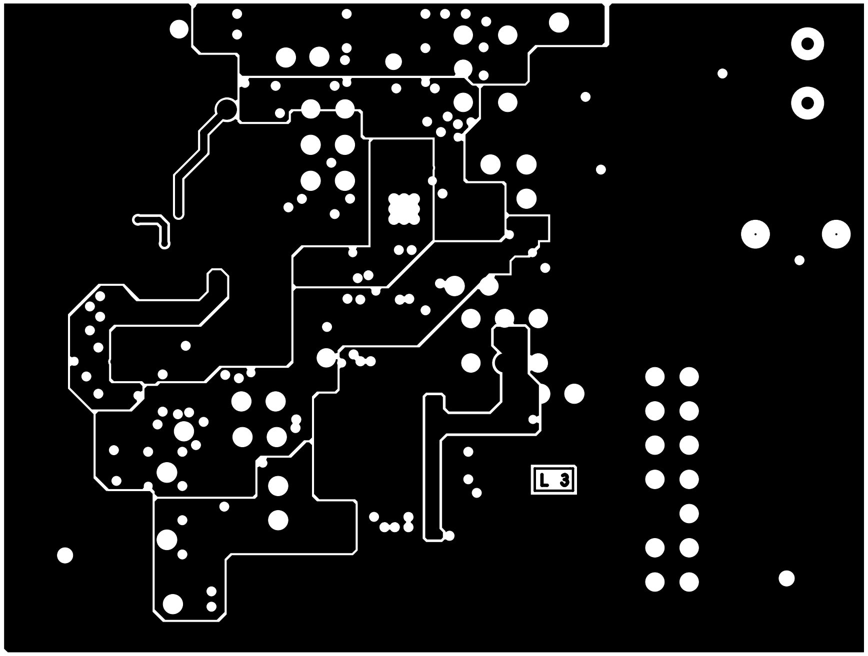
DATE:
03/07/14

PROJECT#:
TI-ECS

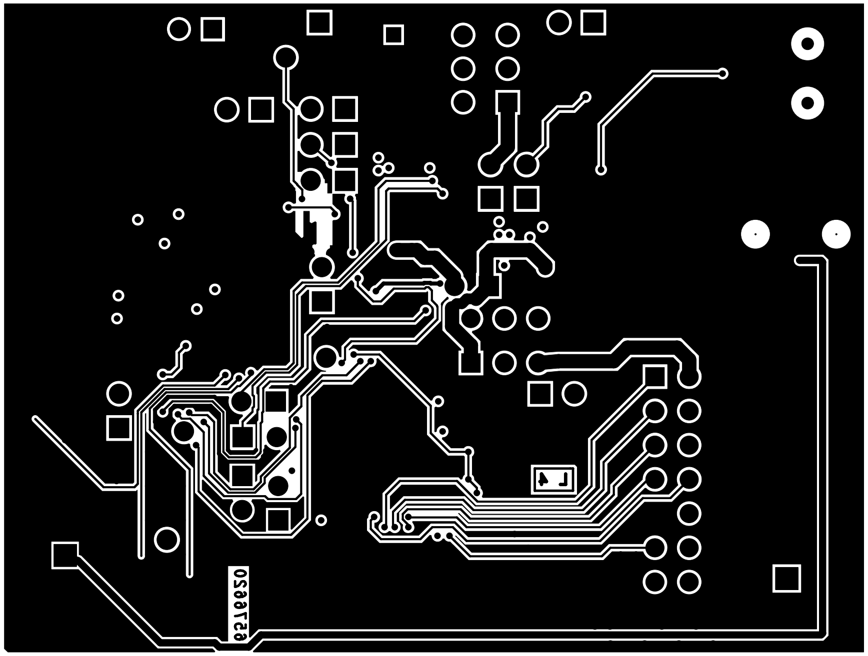
SH: 1 OF: 12



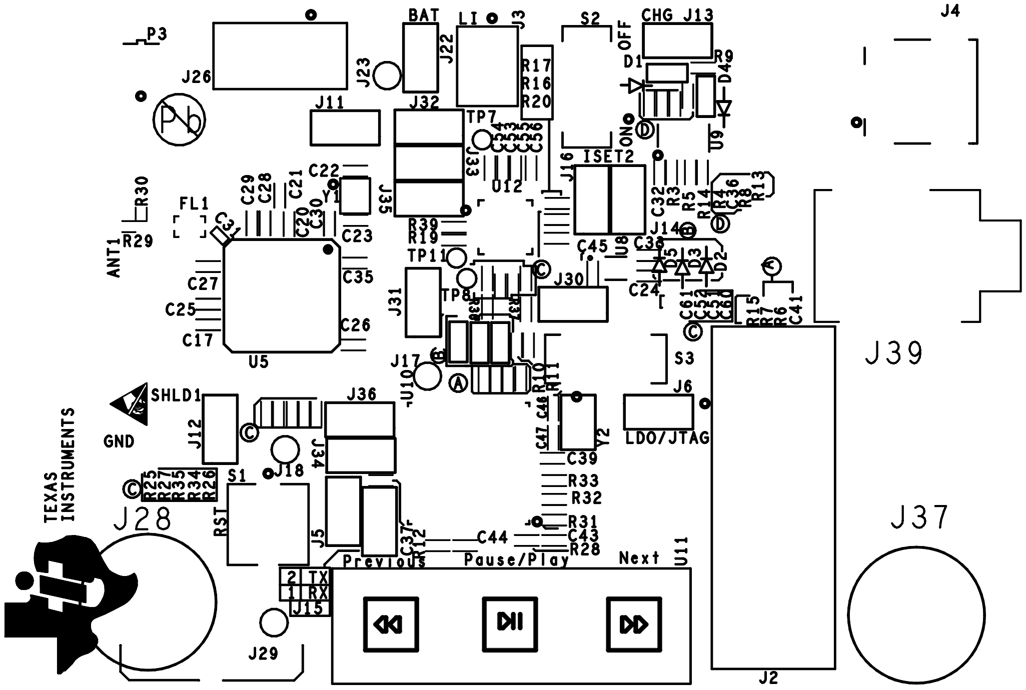
CUSTOMER NAME:				
TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE			DESCRIPTION: LAYER 2 - GND	
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 2 OF: 12



CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE		DESCRIPTION: LAYER 3 - GND/PWR		
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 3 OF: 12



CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE			DESCRIPTION: LAYER 4 - BOTTOM SIDE	
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 4 OF: 12



CUSTOMER NAME: TEXAS INSTRUMENTS

BOARD NAME: BT-MSP-AUDSOURCE

DESCRIPTION: SILKSCREEN - PRIMARY SIDE

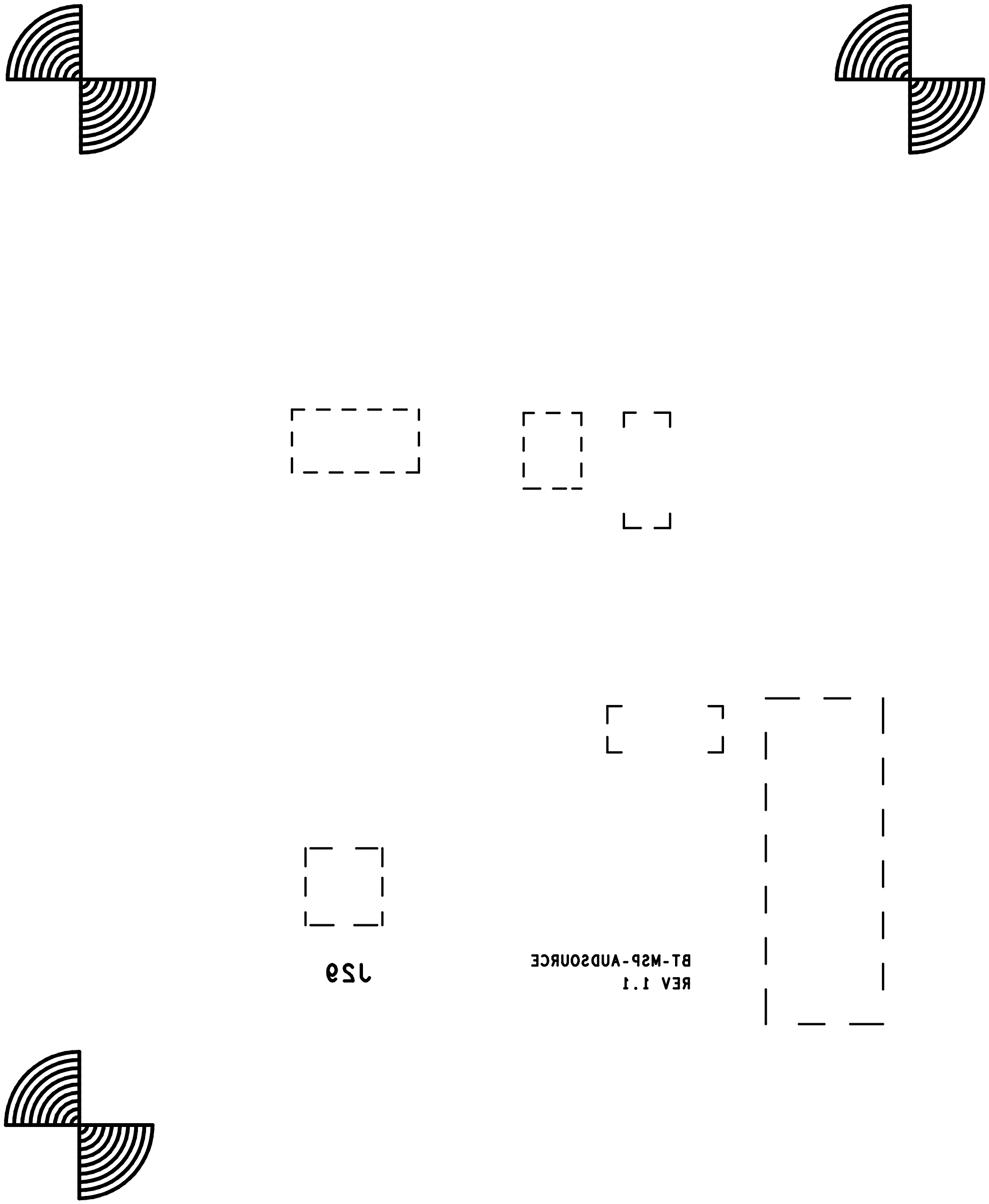
TI TICKET NO: 6576620

REV: 1.1

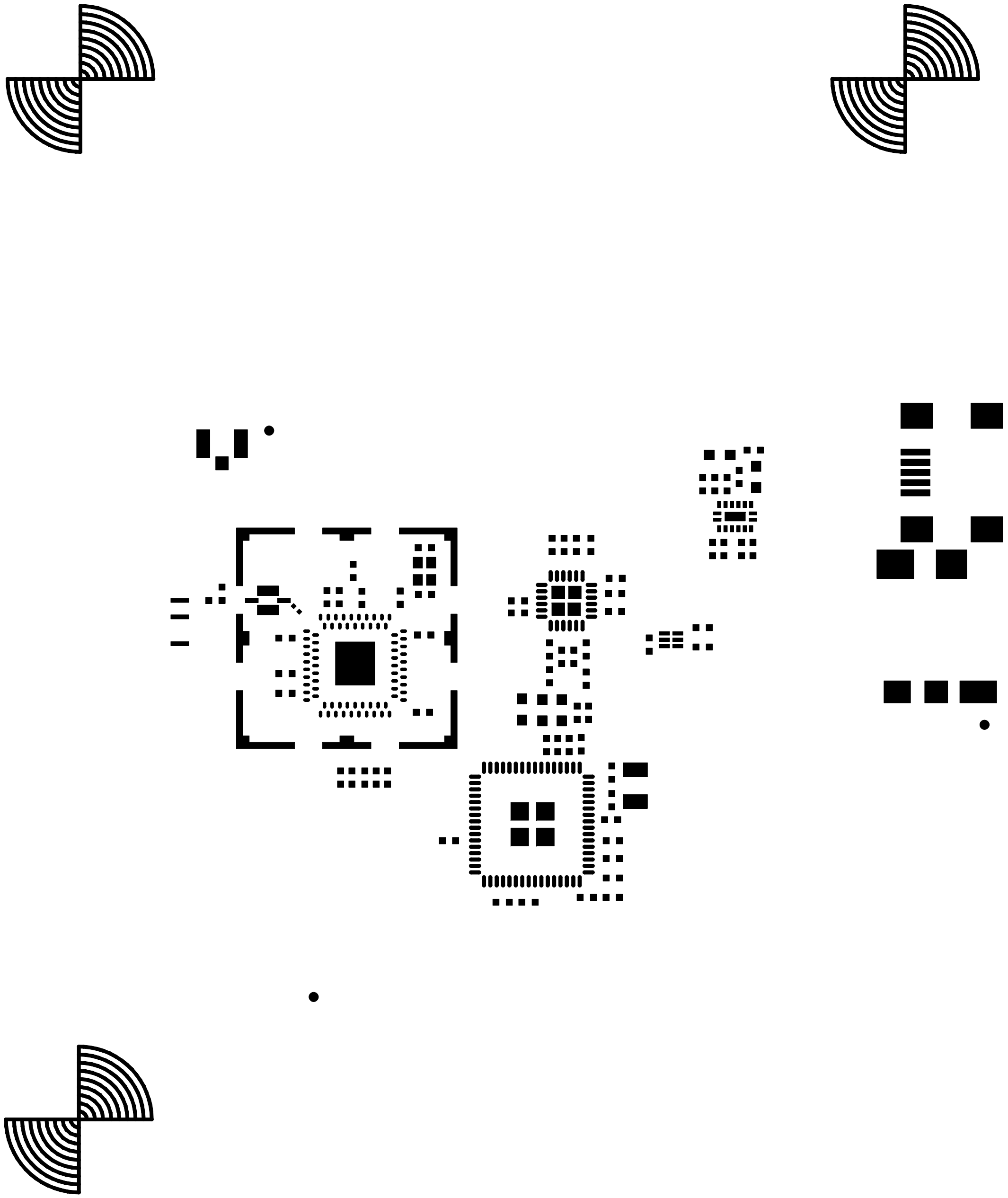
DATE: 03/07/14

PROJECT#: TI-ECS

SH: 5 OF: 12



CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE		DESCRIPTION: SILKSCREEN - SECONDARY SIDE		
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 6 OF: 12



CUSTOMER NAME:
TEXAS INSTRUMENTS

BOARD NAME:
BT-MSP-AUDSOURCE

DESCRIPTION:
SOLDERPASTE - PRIMARY SIDE

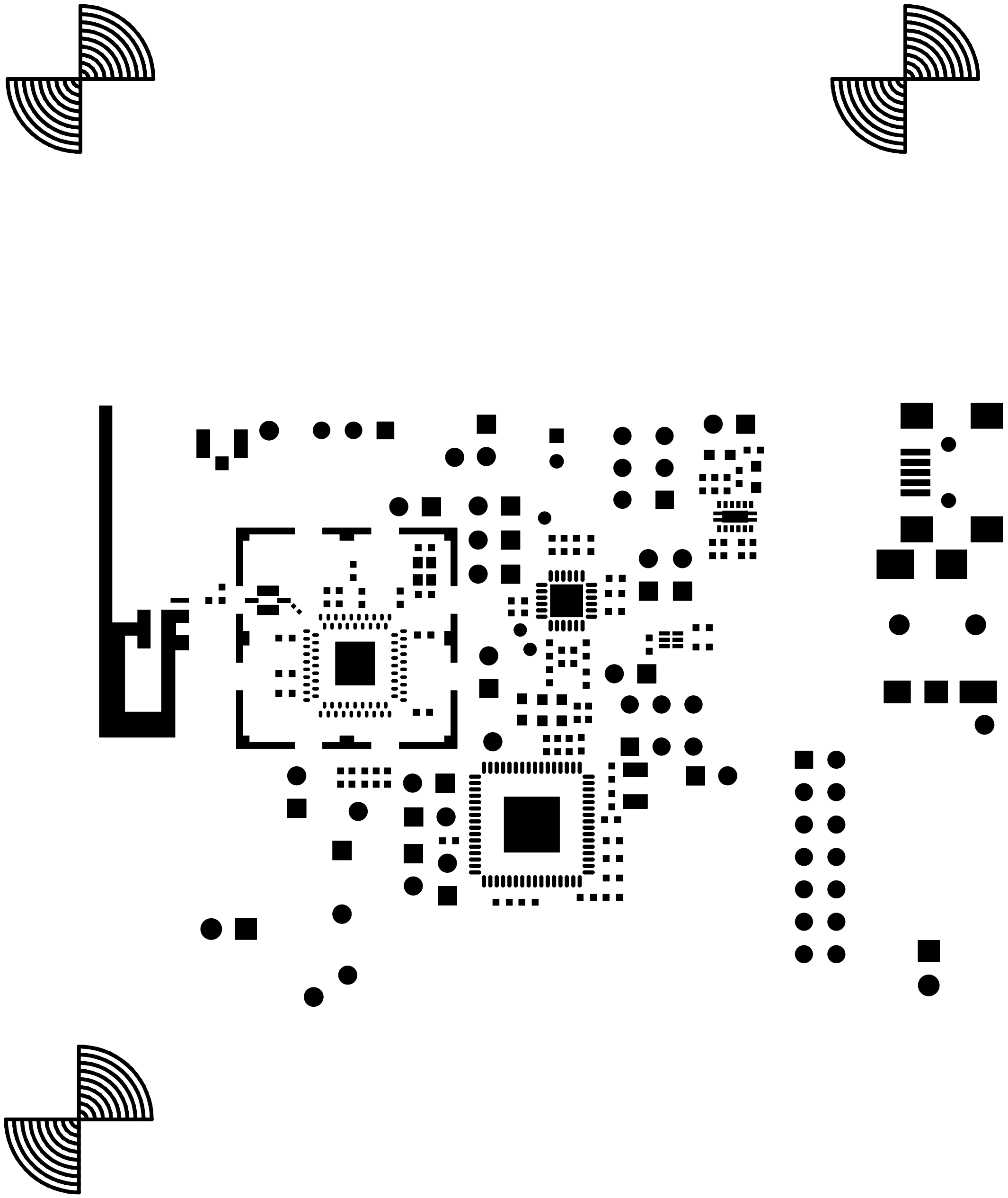
TI TICKET NO:
6576620

REV:
1.1

DATE:
03/07/14

PROJECT#:
TI-ECS

SH: 7
OF: 12



CUSTOMER NAME: TEXAS INSTRUMENTS

BOARD NAME: BT-MSP-AUDSOURCE

DESCRIPTION: SOLDERMASK - PRIMARY SIDE

TI TICKET NO: 6576620

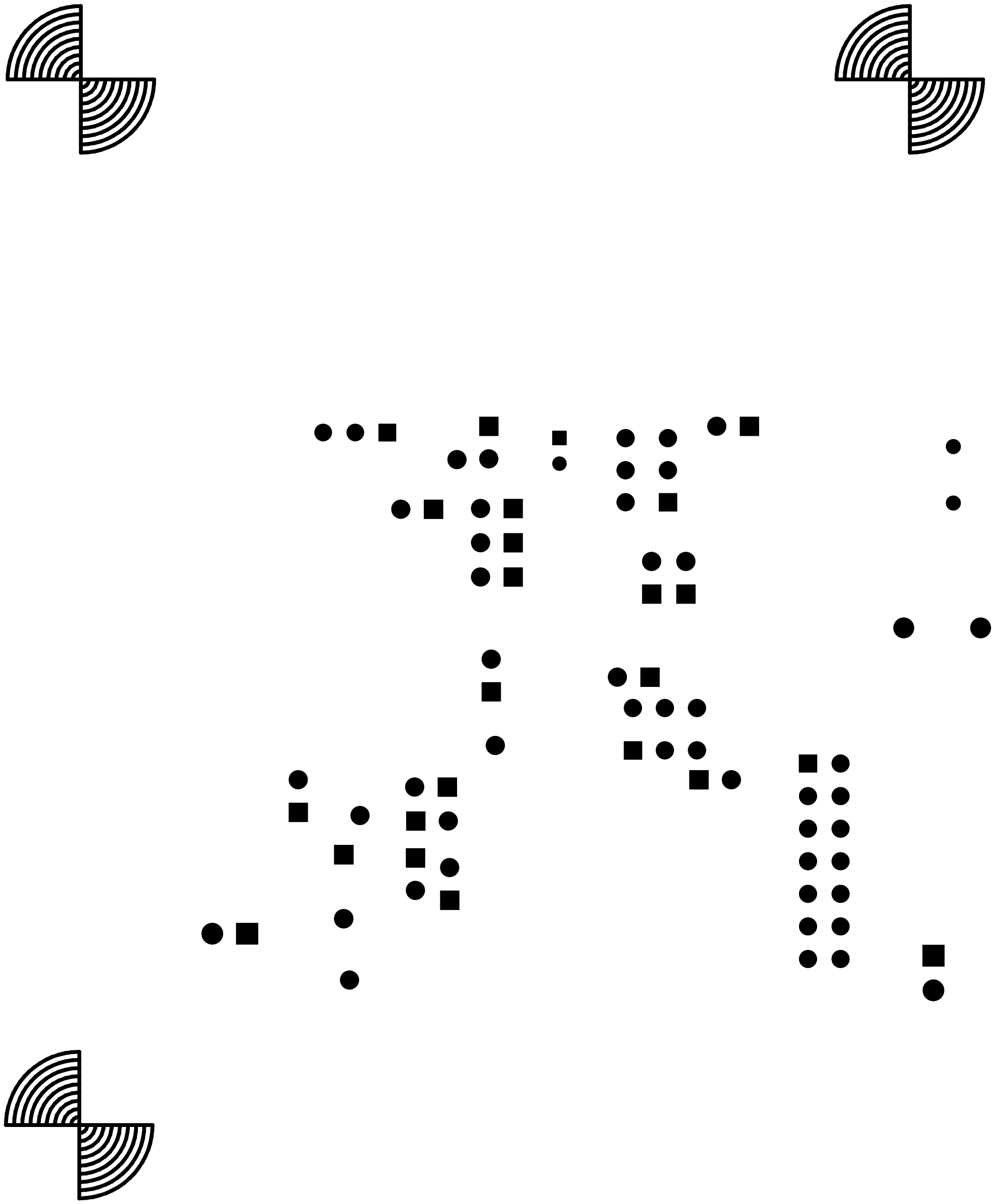
REV: 1.1

DATE: 03/07/14

PROJECT#: TI-ECS

SH: 8

OF: 12



CUSTOMER NAME:
TEXAS INSTRUMENTS

BOARD NAME:	DESCRIPTION:
BT-MSP-AUDSOURCE	SOLDERMASK - SECONDARY SIDE

TI TICKET NO:	REV:	DATE:	PROJECT#:	SH:	OF:
6576620	1.1	03/07/14	TI-ECS	9	12

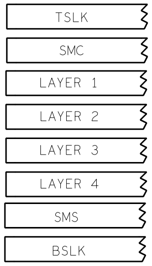
UNLESS OTHERWISE SPECIFIED. ALL NOTES ARE APPLICABLE.
NOTES PRECEDED BY AN UNMARKED "☐" ARE NOT APPLICABLE.

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED.
2. PC SHALL BE FABRICATED TO IPC-6012, CLASS II AND WORKMANSHIP SHALL CONFROM TO IPC-600, CLASS II CURRENT REVISIONS.
3. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH. FOR ALL PLATED THROUGH HOLES.
4. BOARD MATERIAL SHALL BE 180Tg 370HR OR EQUIVALENT. BOARD SHALL MEET OR EXCEED IPC-4101/26. COLOR: NATURAL.
5. BOARD MATERIAL AND CONSTRUCTION TO BE UL 94V-0 APPROVED AND MARKED ON THE FINISHED BOARD.
6. OVERALL BOARD THICKNESS TO BE .062 +/-5% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. MEASURED FROM COPPER TO COPPER.
7. ☒ MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, ☒ LOGO AND DATE CODE TO BE PLACED IN COPPER ON BOTTOM SIDE OF THE BOARD.
8. PLATE ALL EXPOSED AREAS WITH ELECTROLESS NICKEL
   IMMERSION GOLD. NICKEL: 100 MICRO-INCHES MIN
   GOLD: 2-8 MICRO-INCHES MIN
9. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC) COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840 CLASS H, CURRENT REVISION
10. SOLDER MASK CLEARANCE IS GIVEN SAME AS PAD SIZE EXCEPT NPTH AND FIDUCIALS. VENDER SHALL MODIFY THE MASK CLEARANCE AS PER THE REQUIRED MANUFACTURING TOLERANCE.
11. SILKSCREEN-APPLY NON-CONDUCTIVE LPI OR EQUIVALENT PER THE ARTWORK COLOR: WHITE
12. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
13. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .0075 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
14. ☒ BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
15. 6.2 MIL TRACES ON TOP SIDE (LAYER 1) ARE TO BE 50 OHM +/-10% THESE WILL DECOUPLE TO THE GND PLANE ON LAYER 2.
16. ALL VIAS WILL BE FILLED WITH NON-CONDUCTIVE EPOXY.
17. VIAS TO BE TENTED ON BOTH SIDES.

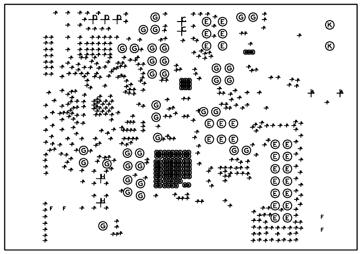
DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	8.0	+0.0/-8.0	PLATED	455
⊗	12.0	+0.0/-12.0	PLATED	90
F	26.0	+0.0/-0.0	PLATED	4
+F	27.5591	+3.0/-3.0	PLATED	2
+P	33.622	+3.0/-3.0	PLATED	3
Ⓔ	35.4	+3.0/-3.0	PLATED	26
Ⓖ	38.0	+3.0/-3.0	PLATED	36
+H	39.3701	+3.0/-3.0	PLATED	4
Ⓚ	35.4	+2.0/-2.0	NON-PLATED	2
+A	62.9921	+2.3622/-2.3622	NON-PLATED	2



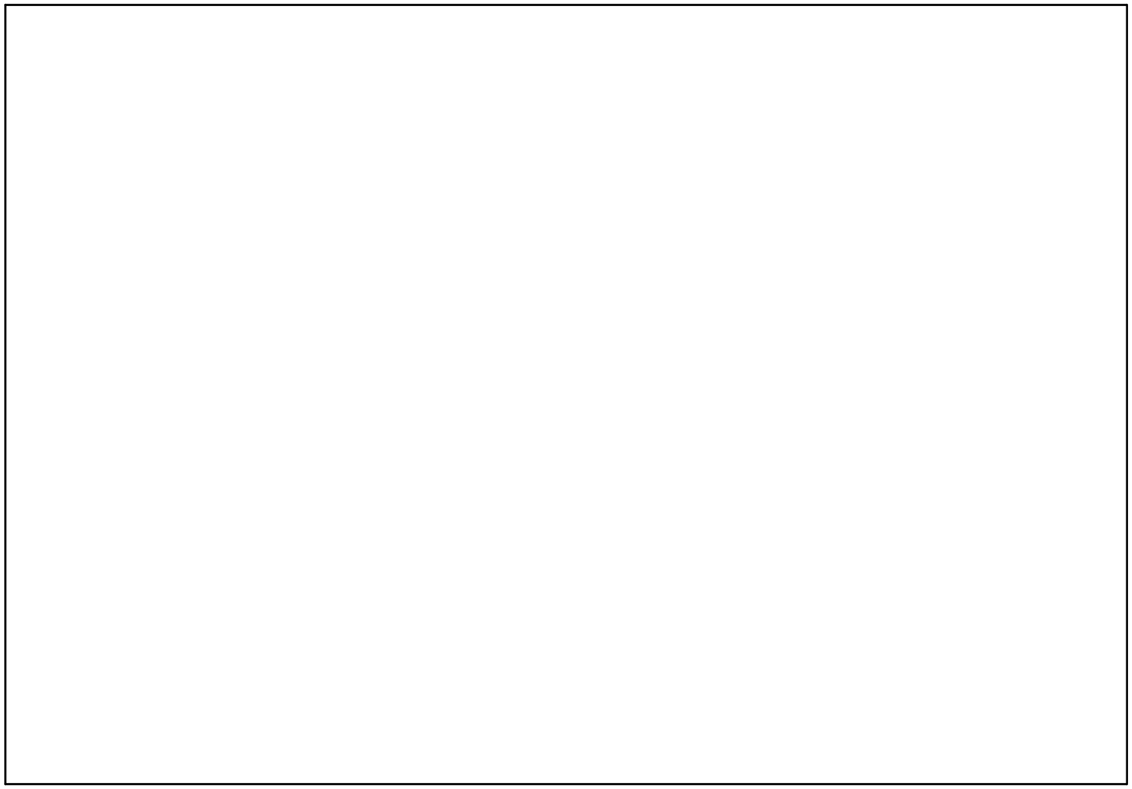
LAYER SCHEDULE
SCALE: NONE



VIEWED FROM TOP SIDE

CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE		DESCRIPTION: FAB DRAWING		
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 10 OF: 12

ALL DIMENSION ARE IN MILS UNLESS OTHERWISE SPECIFIED	TEXAS INSTRUMENTS
DRAWN BY: PRASHANTHA	FABRICATION DRAWING BT-MSP-AUDSOURCE
CHECKED BY: ZAHID HAQ	
APPROVED BY: MIGUEL SANCHEZ	SCALE NONE · REV 1.1 · SIZE B · SHEET 1 OF 1

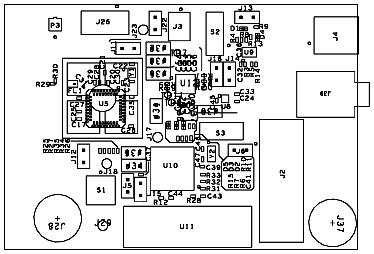


CUSTOMER NAME:
TEXAS INSTRUMENTS

BOARD NAME: BT-MSP-AUDSOURCE	DESCRIPTION: OUTLINE

TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 11 OF: 12

ASSEMBLY TOP SIDE



VIEWED FROM TOP SIDE

CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: BT-MSP-AUDSOURCE		DESCRIPTION: ASSEMBLY TOP		
TI TICKET NO: 6576620	REV: 1.1	DATE: 03/07/14	PROJECT#: TI-ECS	SH: 12 OF: 12

ALL DIMENSION ARE IN MILS UNLESS OTHERWISE SPECIFIED	TEXAS INSTRUMENTS				
DRAWN BY: PRASHANTHA	ASSEMBLY: BT-MSP-AUDSOURCE				
CHECKED BY: ZAHID HAQ					
APPROVED BY: MIIUEL SANCHEZ	SCALE NONE	REV 1.1	SIZE	B	SHEET 1 OF 1

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